

IEC QUALITY ASSESSMENT SYSTEM (IECQ)

covering Electronic Components, Assemblies, Related Materials and Processes

For rules and details of the IECQ visit www.iecq.org

Schedule of Scope to Certificate of Approval Independent Testing Laboratory

IECQ Certificate No.: IECQ-L DEKRA 16.0002
CB Certificate No.: DEKRA-T5A-001

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1. Environmental and Reliability Testing of Electronic Components, Assemblies, and Related Materials

Description test	Standard	Remarks
Consumer / Commercial / Industrial (JESD 47) and Automotive / Military accelerated environment reliability stress tests. (Including: Pre-condition / MSL / Accelerated Temperature-Humidity test / Unbiased Autoclave /Liquid to liquid thermal shock/Air to air thermal shock/ Unbiased HAST/biased HAST/Temperature-Humidity with bias test / Temperature Cycling test / Power and temperature cycling / High and low Temperature storage test / IOL/ Salt)	J-STD-020, JESD22- A101/A102/A103/A104/A105/ A106/A107/A110/A113/A118/A119; IEC- 60068-2-1/2/3/14/38/52/, MIL-STD-202/750/810/883, JESD JEP001; EIA-364-32, EIAJ ED-4701, AEC-Q200-004; AEC-Q005/Q006, JESD22-A105	Or customer specified test
Consumer/ Commercial / Industrial (JESD 47) and Automotive / Military accelerated lifetime simulation tests. (Including: Temperature, Bias, and Operating Life test / early life failure rate / Endurance and Data retention test / Short circuit / Low Temperature Operating Life / Miscellaneous test)	JESD22-A101/A108/A117, MIL-STD-202/750/810/883, AEC-Q100-005/006/008/012, AEC-Q101-004/006, Customer standards	Or customer specified test
Consumer / Commercial / Industrial (JESD 47) and Automotive / Military 2nd level integration platform service. (Including: Pre-SMT/SMT / Temperature Cycling test / Temperature-Humidity test / Drop / Shock / Bending(9point) / Pull and Push test / Solderability / Press / Shear / Hardness / RCA / Durability / Peeling / Terminal Strength / Resistance to Solvents / Resistance to Solder Heat / Hermeticity / Package Warpage Measurement of Surface-Mount Integrated Circuits at Elevated Temperature / Printed Wiring Board Strain Gage Test / Mechanical Compressive Static Stress Test	IPC-7525/9701/9702/9704/9707/9708/A-610, JESD22-A101/A104/A106/A109/A111/B100/B102/B103/B104/B105/B106/B1 07/B108/B110/B111/B112/B113/B115/B116/B117/B119; EIAJ ED-4702, EIA-364-09/13; AEC-Q100-001/010; AEC-Q101-003, AEC-Q200-003/005/006; MIL-STD-202/750/810/883, J-STD-002/003; ASTM D3363, ASTM F2357; SEMI G86-0303, IEC 60068-2-21; IEC-60068-2-14; IPC-TM-650,	Or customer specified test
Electrical Analysis, Sample Preparation (Decap, X-section, etc), NDE (Non-destructive Engineering), Physical & Chemical Analysis (Including Hazardous Substances) and IC package.	IPC-TM-650, IPC-610, J-STD-020, JESD201, EIA-469, IEC62321, EN14582,	Or customer specified test

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